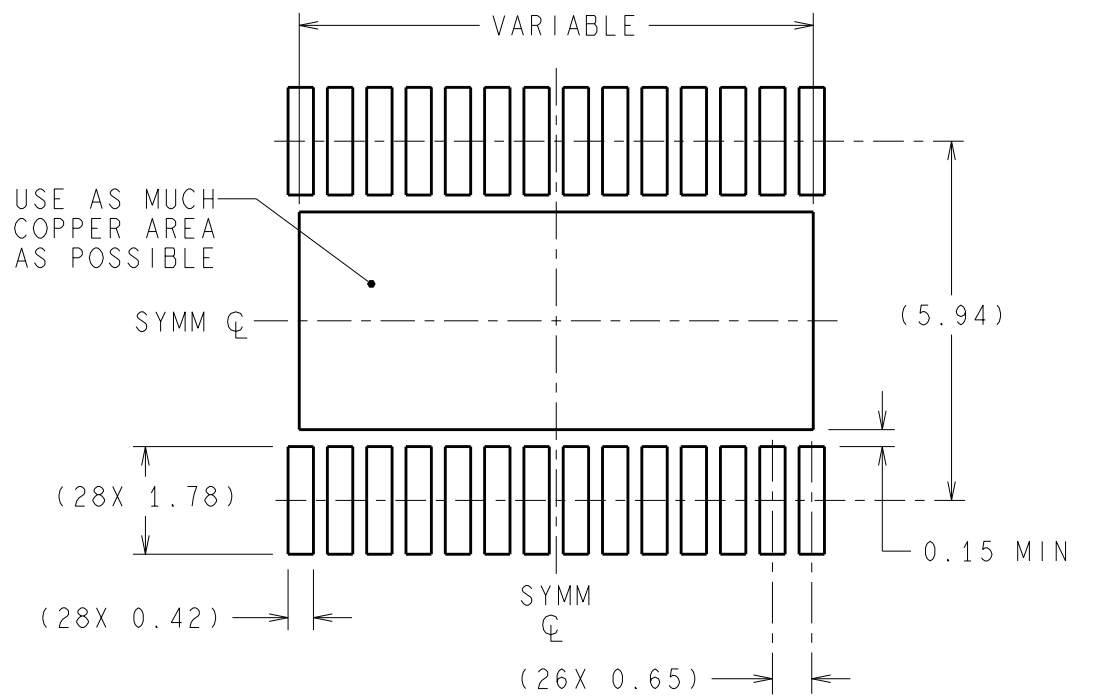
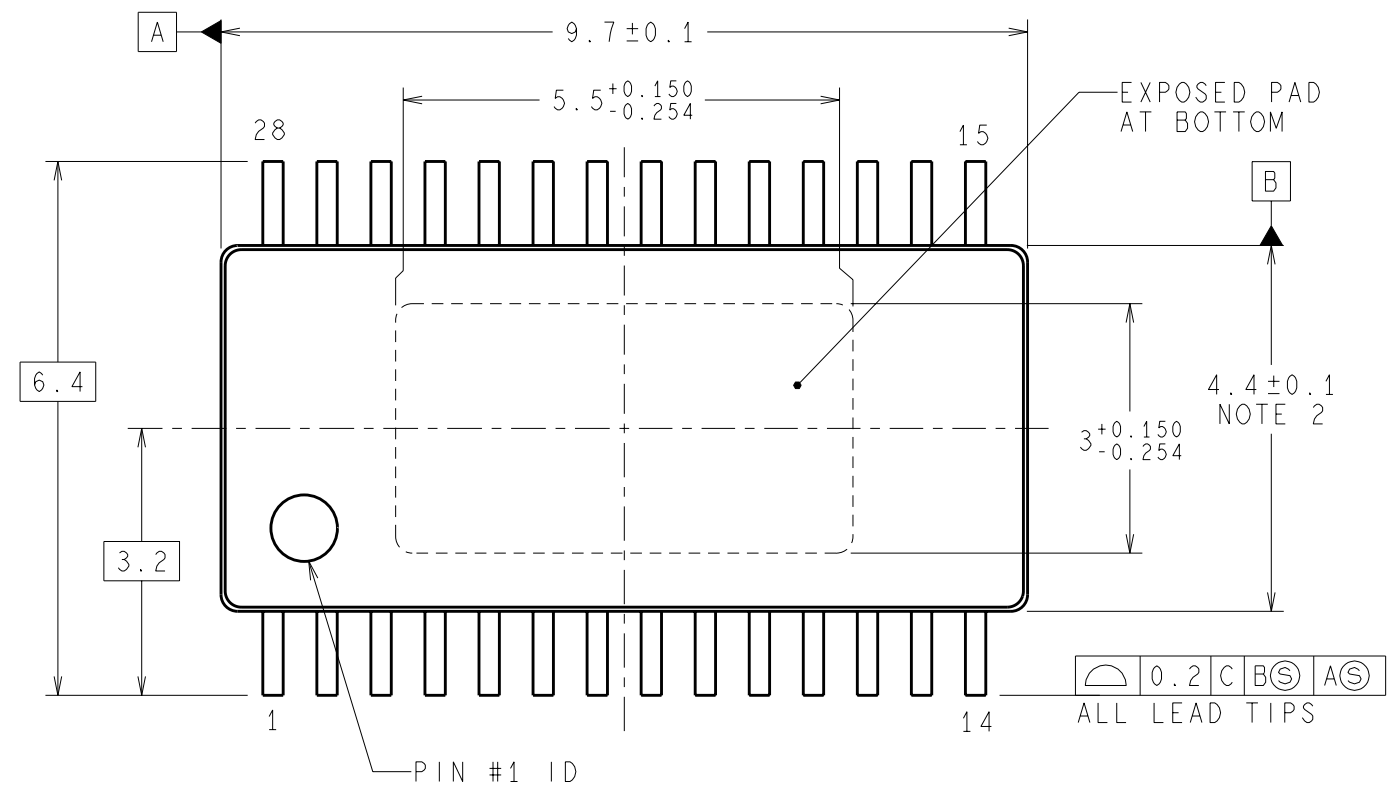
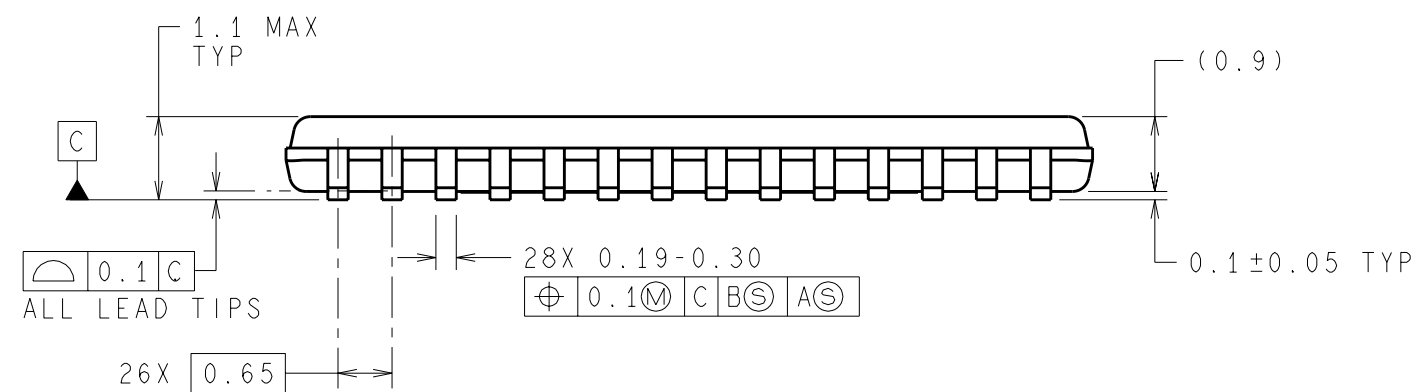


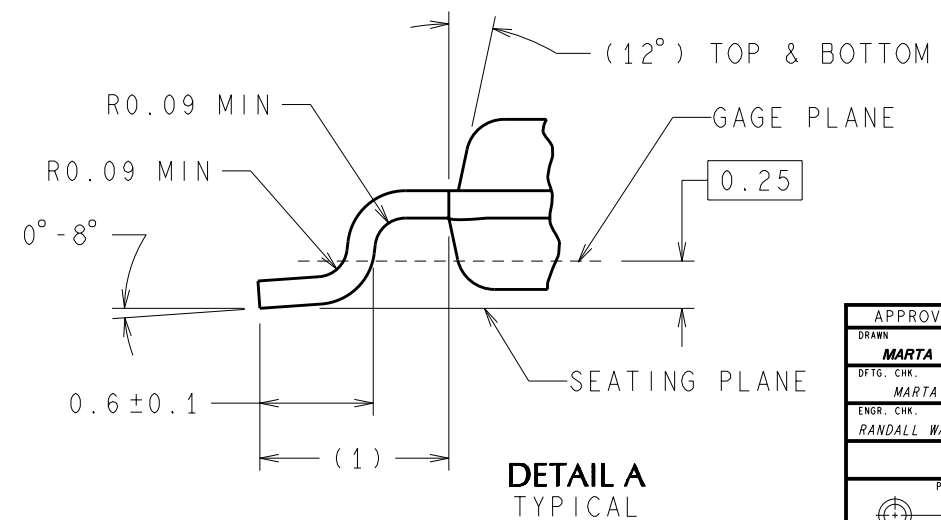
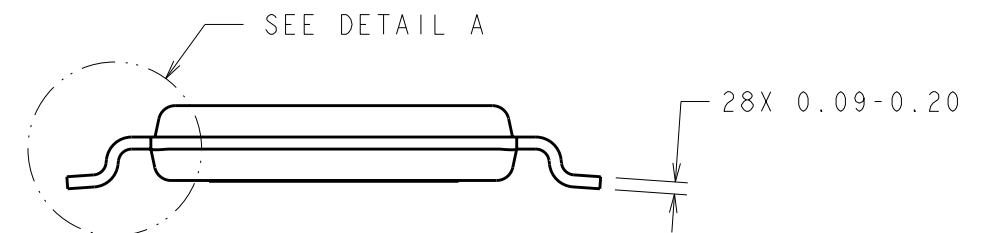
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11918	01/26/1998	MS/JB
B	EXT. PAD TOL'S WERE ±0.15	12098	09/16/1998	MS/JB
C	REVISE PER CURRENT STD.; ADD SOLDER & MOLD FLASH NOTES; UPDATE TITLE; CHG DWG FORMAT TO B SIZE	1043	06/11/2003	TL/RW



RECOMMENDED LAND PATTERN



DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN () FOR REFERENCE ONLY



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- DIMENSION DOES NOT INCLUDE MOLD FLASH.
- REFERENCE JEDEC REGISTRATION MO-153, VARIATION AET.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	MARTA SUCHY	01/26/1998		
DFTG. CHK.	MARTA SUCHY	06/11/2003	MOLDED TSSOP, JEDEC, 9.7x4.4x0.9mm BODY, 28 LD, 0.65mm PITCH, EXP PAD	
ENGR. CHK.	RANDALL WALBERG	06/11/2003		
PROJECTION		SCALE	SIZE	DRAWING NUMBER
		NTS	B	(SC)MKT-MXA28A
MM		FORMERLY: N/A		REV C
				SHEET 1 of 1